

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
PATENT APPLICATION**

Appl. No.	:	TBD	Confirmation No.	TBD
Applicant	:	Donald C. Abbott et al.		
Filed:	:	Herewith		
TC/A.U.	:	TBD		
Examiner	:	TBD		
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Mail Stop Patent Application
Commissioner for Patents
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Alexandria, VA 22313-1450

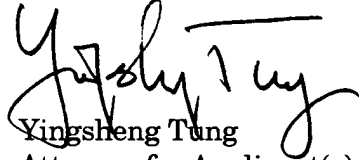
INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97 & 1.98

Sir:

Applicants wish to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO Form 1449. Pursuant to the new rules, copies of the U.S. Patent and Publication herein noted are not enclosed.

Please charge any fees due in connection with the filing of this paper to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. Please credit any excess fees to the same deposit account.

Respectfully submitted,


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FORM PTO-1449
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LIST OF DOCUMENTS CITED BY APPLICANT

(Use several sheets if necessary)

APPLICANT: **Abbott et al.**

FILING DATE

GROUP

Herewith

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U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

“Semiconductor Leadframes Comprising Silver Plating” Tellkamp, U.S. Patent Publication No. US 2002/0047186 A1 Published 25 Apr 2002, filed 17 July 2001

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.